



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant : Wen-Chun ZHENG *et al.*
Serial No.: 10/085,183
Filed : February 27, 2002
Title : SOLID ASSEMBLY OF FLIP-CHIP PACKAGE ATTACHED TO HEAT
REMOVAL DEVICE AND METHOD OF MANUFACTURING SAME

Art Unit : 2815
Examiner : Chris Chu
Confirmation No.: 1430

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

REPLY UNDER 37 CFR § 1.111

In response to the Office Action dated November 28, 2003, please amend the present application as follows and consider the included remarks.

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